

LinCMOS™ TIMER

FEATURES

- Very Low Power Consumption
- Capable of Operation in Astable Mode
- CMOS Output Capable of Swinging Rail to Rail
- High Output-Current Capability
- Output Fully Compatible With CMOS, TTL, and MOS
- Low Supply Current Reduces Spikes During Output Transitions
- Single-Supply Operation From 2 V to 15 V
- Functionally Interchangeable With the NE555; Has Same Pinout
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015.2
- Available in Q-Temp Automotive
 - High Reliability Automotive Applications
 - Configuration Control/Print Support
 - Qualification to Automotive Standards

DESCRIPTION

The TLC555 is a monolithic timing circuit fabricated using the TI LinCMOS process. The timer is fully compatible with CMOS, TTL, and MOS logic and operates at frequencies up to 2 MHz. Because of its high input impedance, this device uses smaller timing capacitors than those used by the NE555. As a result, more accurate time delays and oscillations are possible. Power consumption is low across the full range of power supply voltage.

Like the NE555, the TLC555 has a trigger level equal to approximately one-third of the supply voltage and a threshold level equal to approximately two-thirds of the supply voltage. These levels can be altered by use of the control voltage terminal (CONT). When the trigger input (TRIG) falls below the trigger level, the flip-flop is set and the output goes high. If TRIG is above the trigger level and the threshold input (THRES) is above the threshold level, the flip-flop is reset and the output is low. The reset input (RESET) can override all other inputs and can be used to initiate a new timing cycle. If RESET is low, the flip-flop is reset and the output is low. Whenever the output is low, a low-impedance path is provided between the discharge terminal (DISCH) and GND. All unused inputs should be tied to an appropriate logic level to prevent false triggering.

While the CMOS output is capable of sinking over 100 mA and sourcing over 10 mA, the TLC555 exhibits greatly reduced supply-current spikes during output transitions. This minimizes the need for the large decoupling capacitors required by the NE555.

ORDERING INFORMATION⁽¹⁾

PRODUCT	PACKAGE DESIGNATOR	PACKAGE	ORDERABLE PART NUMBER	PACKAGE QUANTITY
TLC555	TD	Bare die in waffle pack ⁽²⁾	TLC555TDF1	210
			TLC555TDF2	10

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Processing is per the Texas Instruments commercial production baseline and is in compliance with the Texas Instruments Quality Control System in effect at the time of manufacture. Electrical screening consists of DC parametric and functional testing at room temperature only. Unless otherwise specified by Texas Instruments AC performance and performance over temperature is not warranted. Visual Inspection is performed in accordance with MIL-STD-883 Test Method 2010 Condition B at 75X minimum.



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

BARE DIE INFORMATION

DIE THICKNESS	BACKSIDE FINISH	BACKSIDE POTENTIAL	BOND PAD METALLIZATION COMPOSITION	BOND PAD THICKNESS
11 mils.	Silicon with backgrind	Floating	TiW/AlSi (1%)Cu (0.5%)	760 nm

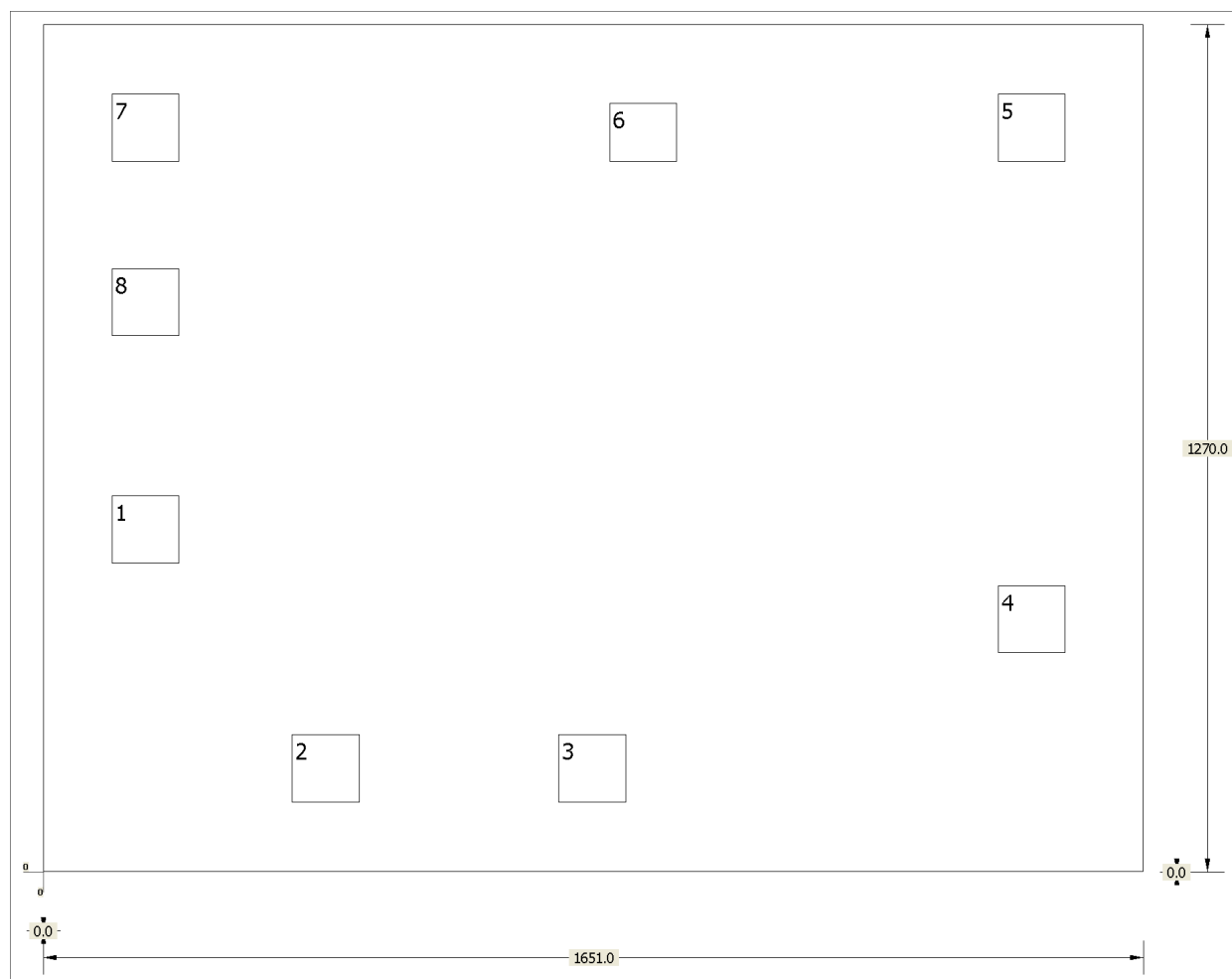


Table 1. Bond Pad Coordinates in Microns⁽¹⁾

DESCRIPTION	PAD NUMBER	X MIN	Y MIN	X MAX	Y MAX
GND	1	102.87	462.28	204.47	563.88
TRIG	2	373.38	104.14	474.98	205.74
OUT	3	773.43	104.14	875.03	205.74
RESET	4	1432.56	327.66	1534.16	429.26
CONT	5	1432.56	1064.26	1534.16	1165.86
THRES	6	849.63	1064.26	951.23	1151.89
DISCH	7	102.87	1064.26	204.47	1165.86
VDD	8	102.87	802.64	204.47	904.24

(1) Substrate N/C.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
TLC555TDF1	ACTIVE			0	210	TBD	Call TI	N / A for Pkg Type	
TLC555TDF2	ACTIVE			0	10	TBD	Call TI	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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